



FGH75T65UPD_F085

650V, 75A Field Stop Trench IGBT

Features

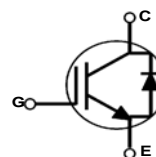
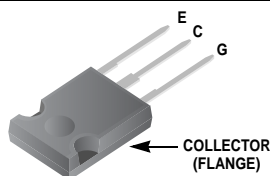
- Maximum Junction Temperature : $T_J = 175^\circ\text{C}$
- Positive Temperature Co-efficient for easy parallel operating
- High current capability
- Low saturation voltage: $V_{CE(sat)} = 1.65\text{V(Typ.)}$ @ $I_C = 75\text{A}$
- High input impedance
- Tightened Parameter Distribution
- RoHS compliant
- Qualified to Automotive Requirements of AEC-Q101

General Description

Using Novel Field Stop Trench IGBT Technology, Fairchild's new series of Field Stop Trench IGBTs offer the optimum performance for Automotive chargers, Solar Inverter, UPS and Digital Power Generator where low conduction and switching losses are essential.

Applications

- Automotive chargers, Converters, High Voltage Auxiliaries
- Solar Inverters, UPS, Digital Power Generator



Absolute Maximum Ratings

| Symbol | Description | Ratings | Units |
|-------------|---|-------------|------------------|
| V_{CES} | Collector to Emitter Voltage | 650 | V |
| V_{GES} | Gate to Emitter Voltage | ± 20 | V |
| I_C | Collector Current @ $T_C = 25^\circ\text{C}$ | 150 | A |
| | Collector Current @ $T_C = 100^\circ\text{C}$ | 75 | A |
| $I_{CM(1)}$ | Pulsed Collector Current | 225 | A |
| I_F | Diode Forward Current @ $T_C = 25^\circ\text{C}$ | 75 | A |
| | Diode Forward Current @ $T_C = 100^\circ\text{C}$ | 50 | A |
| $I_{FM(1)}$ | Pulsed Diode Maximum Forward Current | 225 | A |
| P_D | Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ | 375 | W |
| | Maximum Power Dissipation @ $T_C = 100^\circ\text{C}$ | 187 | W |
| SCWT | Short Circuit Withstand Time @ $T_C = 25^\circ\text{C}$ | 5 | us |
| T_J | Operating Junction Temperature | -55 to +175 | $^\circ\text{C}$ |
| T_{stg} | Storage Temperature Range | -55 to +175 | $^\circ\text{C}$ |
| T_L | Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds | 300 | $^\circ\text{C}$ |

Thermal Characteristics

| Symbol | Parameter | Ratings | Units |
|--------------------------|--------------------------------------|---------|--------------------|
| $R_{\theta JC(IGBT)}(2)$ | Thermal Resistance, Junction to Case | 0.4 | $^\circ\text{C/W}$ |
| $R_{\theta JC(Diode)}$ | Thermal Resistance, Junction to Case | 0.86 | $^\circ\text{C/W}$ |

| Symbol | Parameter | Typ. | Units |
|-----------------|--|------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient (PCB Mount)(2) | 40 | $^\circ\text{C/W}$ |

Package Marking and Ordering Information

| Device Marking | Device | Package | Packing Type | Qty per Tube |
|----------------|------------------|---------|--------------|--------------|
| FGH75T65UPD | FGH75T65UPD_F085 | TO-247 | Tube | 30ea |

For Fairchild's definition of "green" Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs_green.html.

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|--------------------------------------|--|---|------|------|------|-------|
| Off Characteristics | | | | | | |
| BV_{CES} | Collector to Emitter Breakdown Voltage | $V_{GE} = 0V, I_C = 1mA$ | 650 | - | - | V |
| $\frac{\Delta BV_{CES}}{\Delta T_J}$ | Temperature Coefficient of Breakdown Voltage | $V_{GE} = 0V, I_C = 1mA$ | - | 0.65 | - | V/°C |
| I_{CES} | Collector Cut-Off Current | $V_{CE} = V_{CES}, V_{GE} = 0V$ | - | - | 250 | μA |
| | | I_{CES} at 80%* $BV_{CES}, 175^\circ C$ | - | - | 3600 | |
| I_{GES} | G-E Leakage Current | $V_{GE} = V_{GES}, V_{CE} = 0V$ | - | - | ±400 | nA |
| On Characteristics | | | | | | |
| $V_{GE(th)}$ | G-E Threshold Voltage | $I_C = 75mA, V_{CE} = V_{GE}$ | 4.0 | 6.0 | 7.5 | V |
| $V_{CE(sat)}$ | Collector to Emitter Saturation Voltage | $I_C = 75A, V_{GE} = 15V$ | - | 1.69 | 2.3 | V |
| | | $I_C = 75A, V_{GE} = 15V, T_C = 175^\circ C$ | - | 2.21 | - | V |
| Dynamic Characteristics | | | | | | |
| C_{ies} | Input Capacitance | $V_{CE} = 30V, V_{GE} = 0V, f = 1MHz$ | - | 5665 | - | pF |
| C_{oes} | Output Capacitance | | - | 205 | - | pF |
| C_{res} | Reverse Transfer Capacitance | | - | 100 | - | pF |
| Switching Characteristics | | | | | | |
| $t_{d(on)}$ | Turn-On Delay Time | $V_{CC} = 400V, I_C = 75A, R_G = 3\Omega, V_{GE} = 15V, \text{Inductive Load}, T_C = 25^\circ C$ | - | 32 | 48 | ns |
| t_r | Rise Time | | - | 43 | 71 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | - | 166 | 216 | ns |
| t_f | Fall Time | | - | 24 | 33 | ns |
| E_{on} | Turn-On Switching Loss | | - | 2.85 | 4.80 | mJ |
| E_{off} | Turn-Off Switching Loss | | - | 1.20 | 1.60 | mJ |
| E_{ts} | Total Switching Loss | | - | 4.05 | 5.3 | mJ |
| $t_{d(on)}$ | Turn-On Delay Time | $V_{CC} = 400V, I_C = 75A, R_G = 3\Omega, V_{GE} = 15V, \text{Inductive Load}, T_C = 175^\circ C$ | - | 30 | - | ns |
| t_r | Rise Time | | - | 57 | - | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | - | 176 | - | ns |
| t_f | Fall Time | | - | 21 | - | ns |
| E_{on} | Turn-On Switching Loss | | - | 4.45 | - | mJ |
| E_{off} | Turn-Off Switching Loss | | - | 1.60 | - | mJ |
| E_{ts} | Total Switching Loss | | - | 6.05 | - | mJ |
| T_{sc} | Short Circuit Withstand Time | $V_{GE} = 15V, V_{CC} \leq 400V, R_g = 10 \Omega$ | 5 | - | - | us |

Notes:

1: Repetitive rating: Pulse width limited by max junction temperature.

2: $R_{th(jc)}$ for TO-247 : according to Mil standard 883-1012 test method. $R_{th(ja)}$ for TO-247 : according to JESD51-2, test method environmental condition and JESD51-10, test boards for through hole perimeter leaded package thermal measurements.

JESD51-3 : Low Effective Thermal Conductivity Test Board for Leaded Surface Mount Package.

Electrical Characteristics of the IGBT (Continued)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max | Units |
|----------|--------------------------|---|------|------|-----|-------|
| Q_g | Total Gate Charge | $V_{CE} = 400V, I_C = 75A,$ $V_{GE} = 15V$ | - | 385 | 578 | nC |
| Q_{ge} | Gate to Emitter Charge | | - | 45 | 68 | nC |
| Q_{gc} | Gate to Collector Charge | | - | 210 | 315 | nC |

Electrical Characteristics of the Diode $T_C = 25^\circ C$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max | Units | |
|-----------|-------------------------------|-----------------------------------|---------------------|------|-----|-------|---------|
| V_{FM} | Diode Forward Voltage | $I_F = 50A$ | $T_C = 25^\circ C$ | - | 2.1 | 2.6 | V |
| | | | $T_C = 175^\circ C$ | - | 1.7 | - | |
| E_{rec} | Reverse Recovery Energy | $I_F = 50A, di_F/dt = 200A/\mu s$ | $T_C = 175^\circ C$ | - | 40 | - | μJ |
| t_{rr} | Diode Reverse Recovery Time | | $T_C = 25^\circ C$ | - | 43 | 85 | ns |
| | | | $T_C = 175^\circ C$ | - | 162 | - | |
| Q_{rr} | Diode Reverse Recovery Charge | | $T_C = 25^\circ C$ | - | 83 | 170 | nC |
| | | $T_C = 175^\circ C$ | - | 805 | - | | |

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

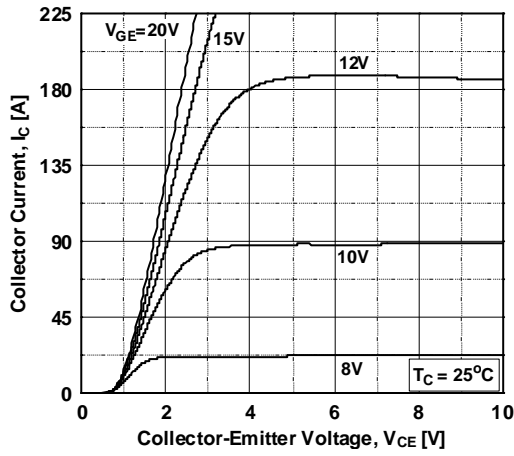


Figure 2. Typical Output Characteristics

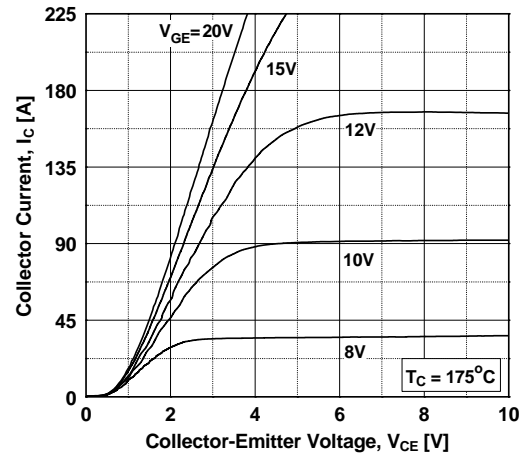


Figure 3. Typical Saturation Voltage Characteristics

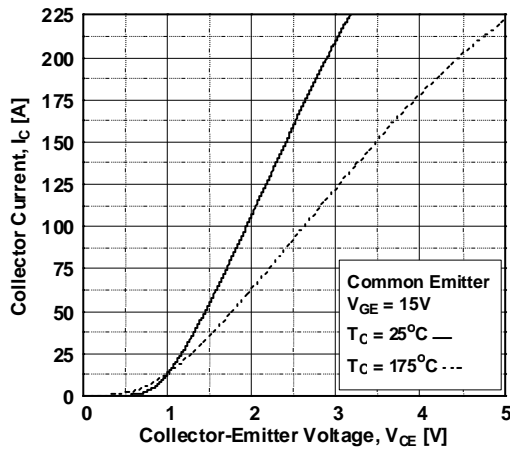


Figure 4. Transfer Characteristics

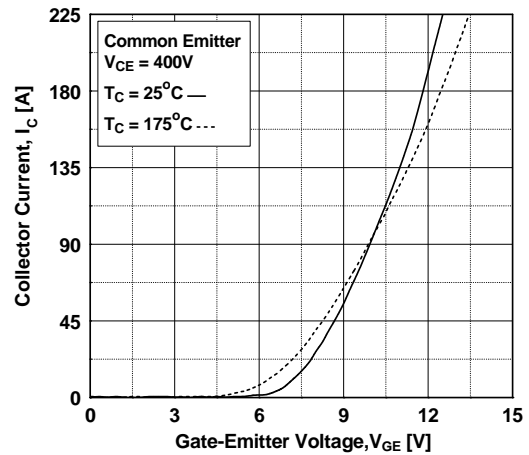


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

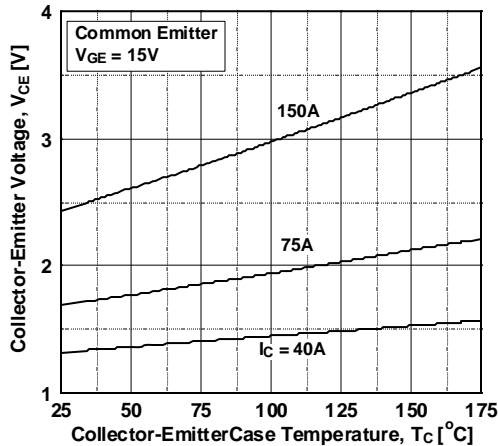
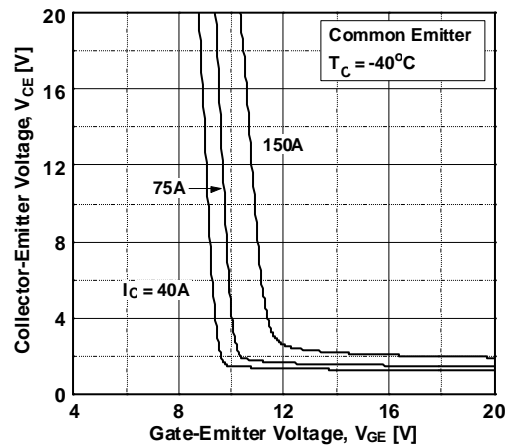


Figure 6. Saturation Voltage vs. Vge



Typical Performance Characteristics

Figure 7. Saturation Voltage vs. V_{GE}

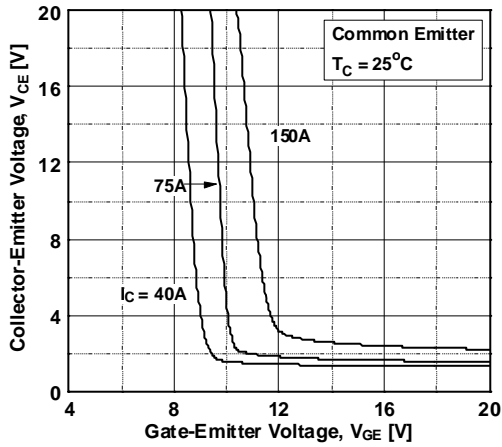


Figure 8. Saturation Voltage vs. V_{GE}

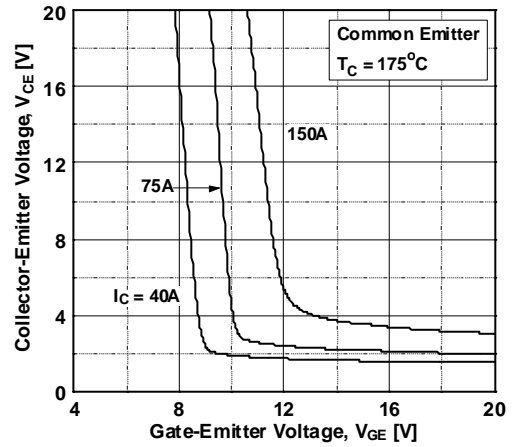


Figure 9. Capacitance Characteristics

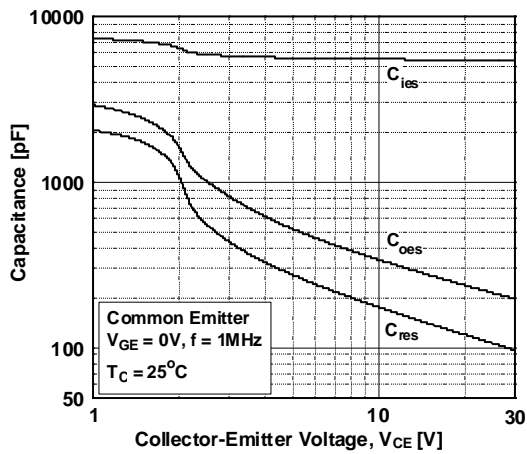


Figure 10. Gate charge Characteristics

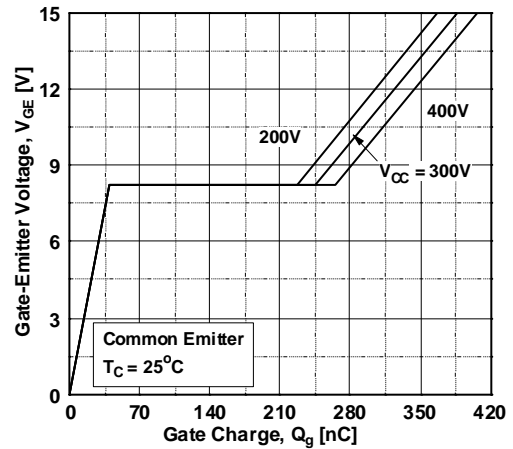


Figure 11. SOA Characteristics

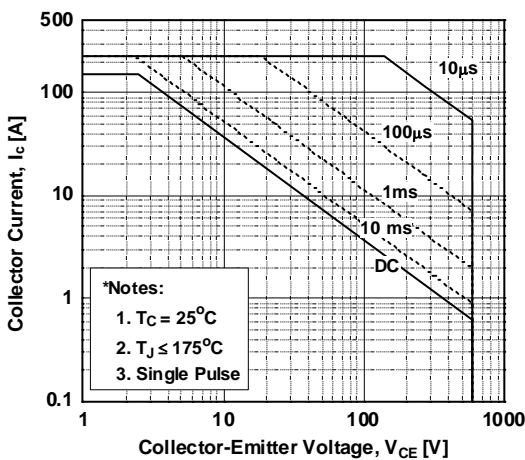
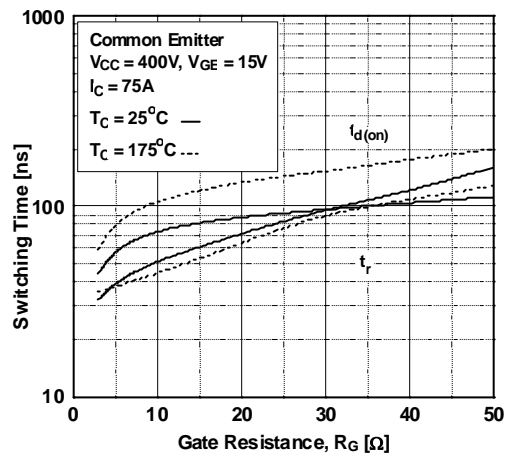


Figure 12. Turn-on Characteristics vs. Gate Resistance



Typical Performance Characteristics

Figure 13. Turn-off Characteristics vs. Gate Resistance

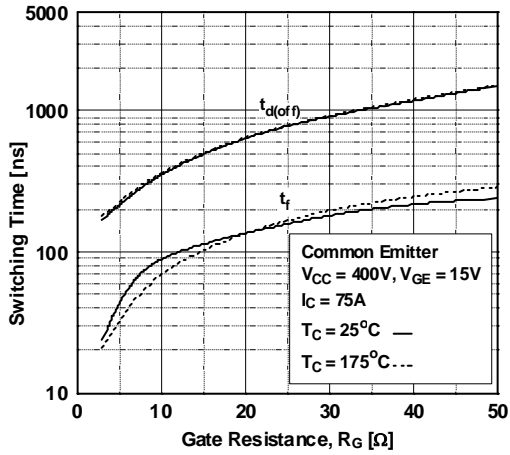


Figure 14. Turn-on Characteristics vs. Collector Current

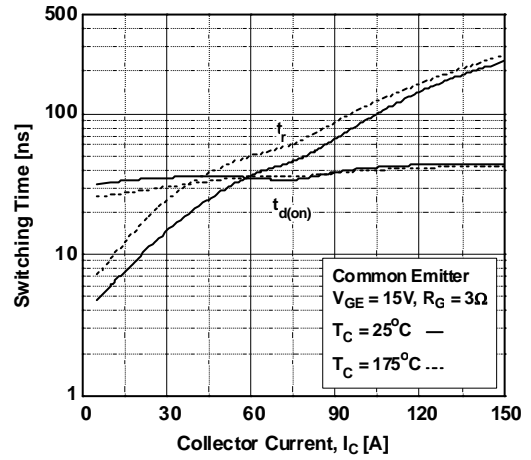


Figure 15. Turn-off Characteristics vs. Collector Current

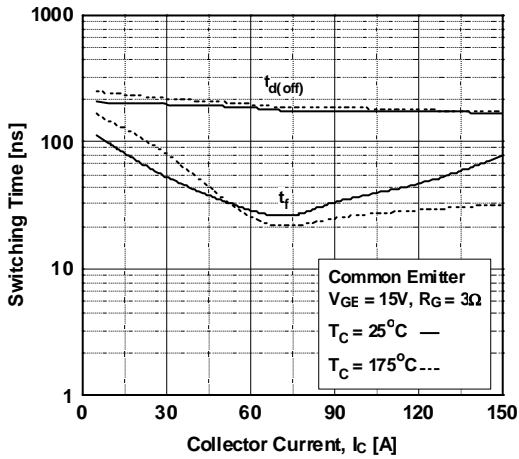


Figure 16. Switching Loss vs. Gate Resistance

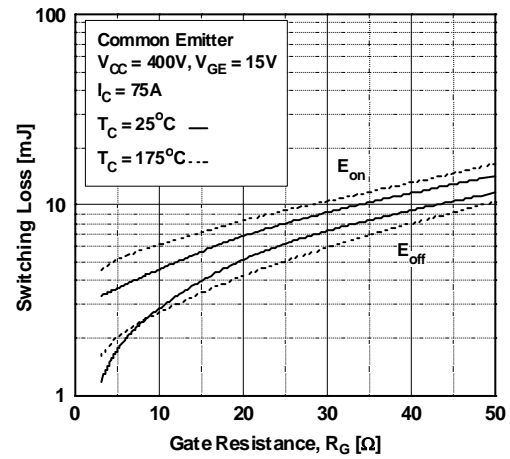


Figure 17. Switching Loss vs. Collector Current

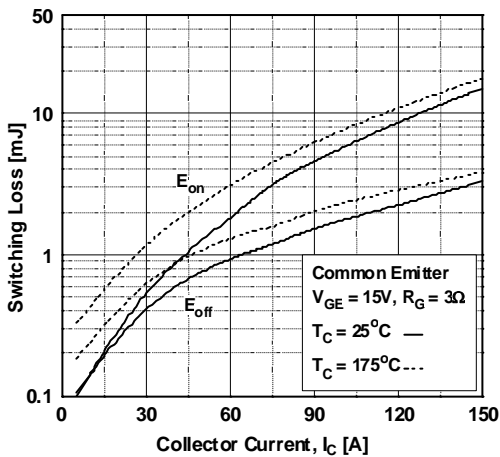
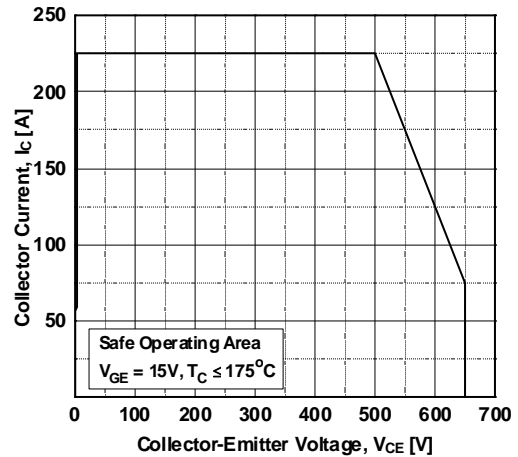


Figure 18. Turn off Switching SOA Characteristics



Typical Performance Characteristics

Figure 19. Current Derating

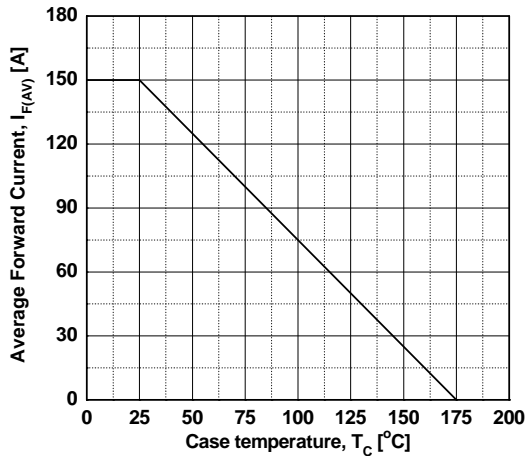


Figure 20. Load Current Vs. Frequency

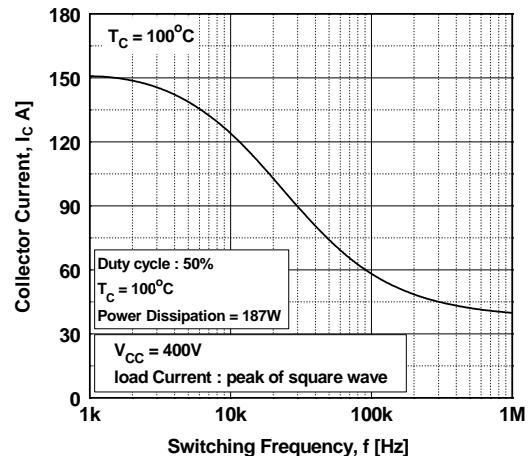


Figure 21. Forward Characteristics

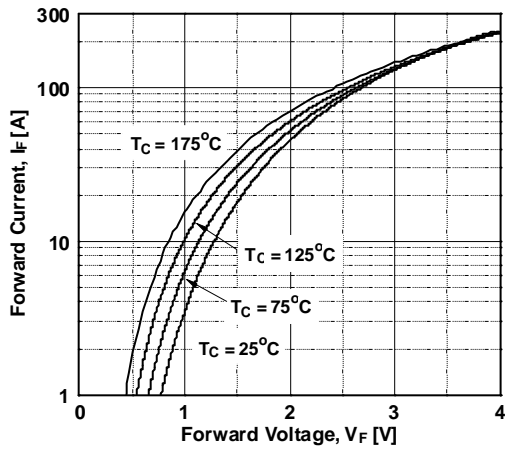


Figure 22. Reverse Recovery Current

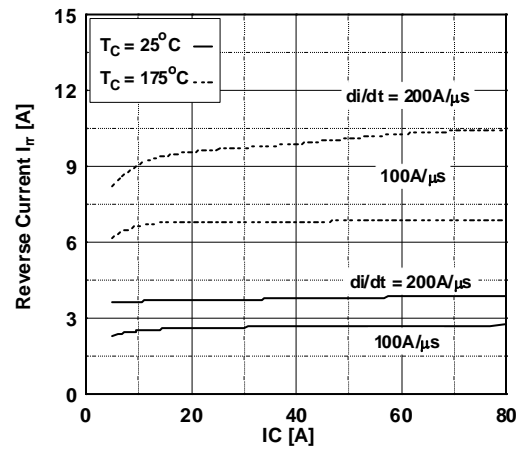


Figure 23. Stored Charge

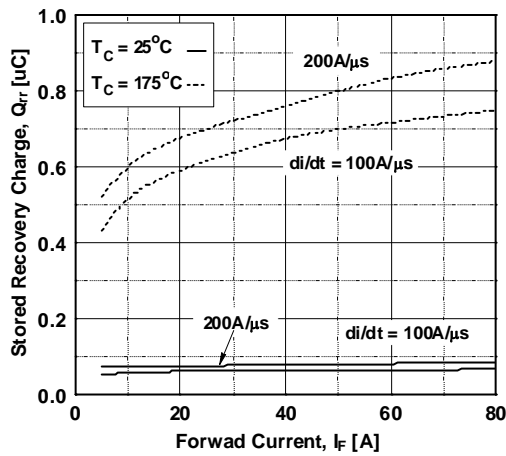
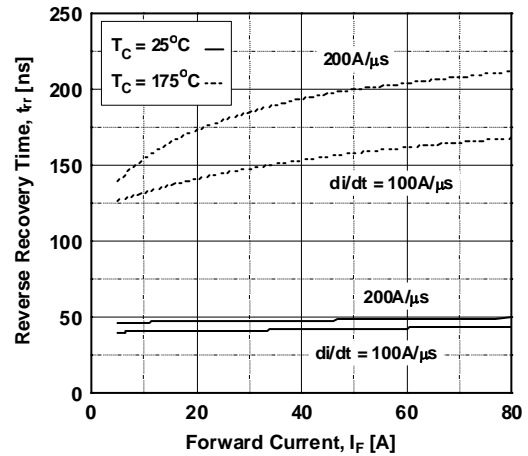


Figure 24. Reverse Recovery Time



Typical Performance Characteristics

Figure 25. Transient Thermal Impedance of IGBT

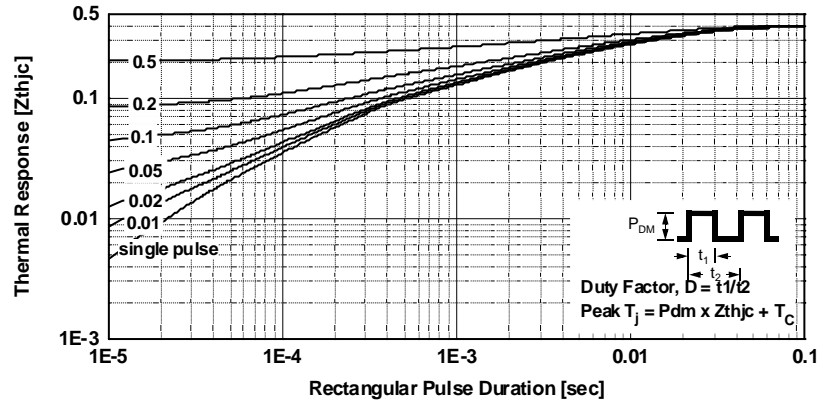
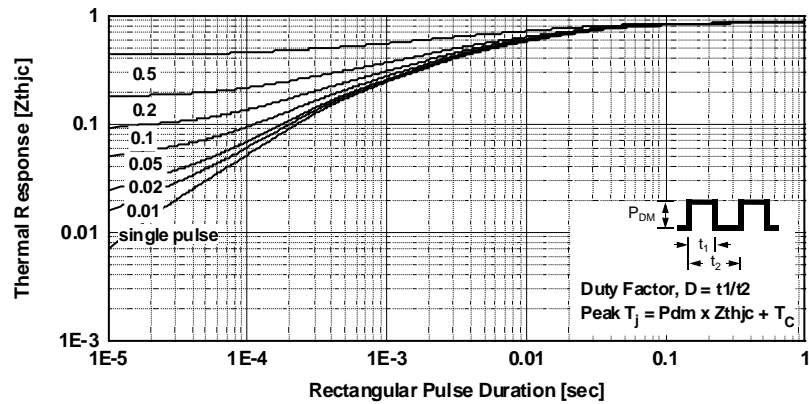


Figure 26. Transient Thermal Impedance of Diode





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|--------------------------|-----------------------|---|
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| Preliminary | First Production | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
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